

MOS INTEGRATED CIRCUIT μ PD16654

150/154 OUTPUT TFT-LCD GATE DRIVE

The μ PD16654 is a TFT-LCD gate driver. Because this gate driver has a level shift circuit for logic input, it can output a high gate scanning voltage in response to a CMOS-level input.

Moreover, it can also drive both the XGA/SXGA panel (154 outputs) and SVGA panel (150 outputs) by changing the number of outputs over between 150 and 154.

FEATURES

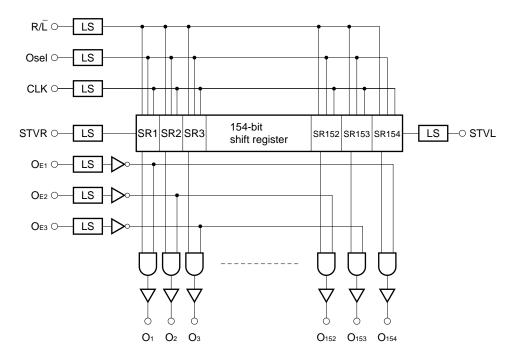
- High breakdown voltage output (ON/OFF range: VDD2-VEE2 = 40 V MAX.)
- 3.3 V CMOS level input
- Number of output select function (150/154 outputs)

ORDERING INFORMATION

Part Number	Package
μPD16654N-×××	TCP (TAB package)

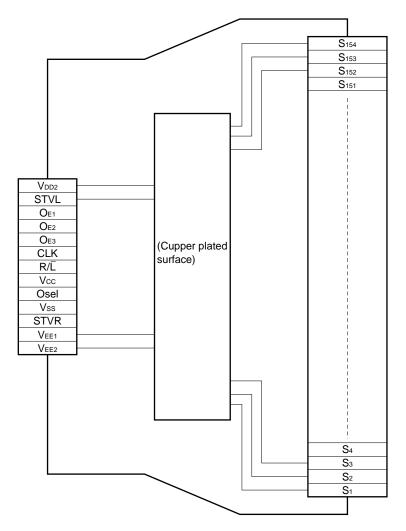
The TCP's external shape is customized. To order your TCP's external shape, please contact an NEC salesperson.

1. BLOCK DIAGRAM



LS (level shifter): Interfaces between 3.3 V CMOS level and VDD2-VEE1 level.

2. PIN CONFIGURATION (µPD16654N-×××)



Caution This figure does not specify the TCP package.

3. PIN FUNCTIONS

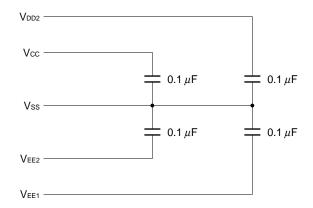
Pin Symbol	Pin Name	Description
O1 to O154	Driver output pins	Scan signal output pins that drive the gate electrode of a TFT-LCD. The status of each output pin changes in synchronization with the rising edge of shift clock CLK. The output voltage of the driver is VDD2 to VEE2.
STVR STVL	Start pulse input/output pin	Input/output pin of the internal shift register. Start pulse signal is read at the rising edge of shift clock CLK and a scan signal is output from the driver output pin. The interface of this terminal is CMOS of 3.3 V. When O _{sel} signal is Low level, start pulse goes up to high level at the 154th falling edge of shift clock CLK and goes down to low level at the 155th falling edge. And when O _{sel} signal is High level, start pulse goes up to high level at the 150th falling edge of shift clock CLK and goes down to low level at the 150th falling edge. The output level is Vcc-Vss (logic level).
CLK	Shift clock input	Shift clock input for the internal shift register. The contents of internal shift register is shifted at the rising edge of CLK.
R/L	Shift direction switching input	
Oe1 Oe2 Oe3	Enable input	This pin fixes the driver output to the L level when it is high. However, the shift register is not cleared. And, output enable actuation is asynchronous in the clock. And, refer to "RELATIONS OF ENABLE INPUT AND OUTPUT TERMINAL".
Osel	Number of output select input	Selects the number of outputs. O _{sel} = L : 154 outputs (SVGA) O _{sel} = H: 150 outputs (VGA, XGA, SXGA) When O _{sel} = H (150 outputs), O ₇₆ through O ₇₉ outputs of the shift register are fixed to the VEE2 level. Fix this pin to Vcc (VDD2) or Vss (VEE1) on TCP.
Vdd2	Positive power supply for driver	Shared with internal logic and driver
Vcc	Reference power supply	3.3 V \pm 0.3 V. Reference power supply for level shifter: LS
Vss	Ground (GND)	Connect this pin to the system ground.
Vee1	Negative power supply for internal logic	Negative power supply for internal logic
Vee2	Negative power supply for driver	Negative power supply for driver

Caution 1. Power ON/OFF sequence

To prevent the μ PD16654 from damage due to latch up, turn on power in the order V_{CC} \rightarrow V_{EE1}, V_{EE2} and V_{DD2} \rightarrow logic input. Turn off power in the reverse order. Observe these power sequences even during transition period.

Caution 2. Inserting bypass capacitor

Because the internal logic operates at a high voltage (V_{DD2}-V_{EE1}), insert a bypass capacitor of about 0.1 μ F between the respective power pins as shown below to secure the noise margin of V_{IH} and V_{IL}.



Do not input a switching signal to the Osel pin that selects the number of outputs. Connect this pin to Vcc or Vss (VEE1).

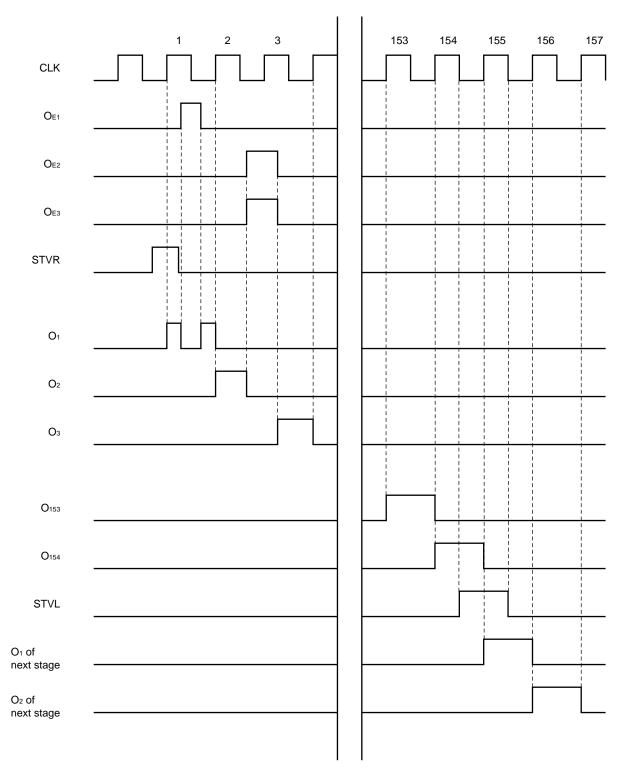
4. RELATIONS OF ENABLE INPUT AND OUTPUT TERMINAL

Switching is possible for 154/150 with μ PD16654 by the O_{sel} terminal. And, the output terminal which can be controlled by the enable signal changes as follows along with this function.

154 ou	It TCP	150 ou	t Mode	
154 out Mode (O _{sel} = L)	150 out Mode (O _{sel} = H)	154 out Mode (O _{sel} = L)	150 out Mode (O _{sel} = H)	
O1 (OE1)	O1 (OE1)	O1 (OE1)	O1 (OE1)	
O2 (OE2)	O2 (OE2)	O2 (OE2)	O2 (OE2)	
O3 (OE3)	O3 (OE3)	Оз (Оез)	O3 (OE3)	
O4 (OE1)	O4 (OE1)	O4 (OE1)	O4 (OE1)	
O5 (OE2)	O5 (OE2)	O5 (OE2)	O5 (OE2)	
O6 (OE3)	O6 (OE3)	O6 (OE3)	O6 (OE3)	
•	•	•	•	
•	•	•	•	
O72 (OE3)	О72 (Оез)	O72 (OE3)	O72 (OE3)	
O73 (OE1)	O73 (OE1)	O73 (OE1)	O73 (OE1)	
O74 (OE2)	O74 (OE2)	O74 (OE2)	O74 (OE2)	
O75 (OE3)	О75 (ОЕ3) О75 (ОЕ3)		O75 (Oe3)	
O76 (OE1)	O76 (OE1) Vout = VEE2			
O77 (OE2)	$V_{\text{out}} = V_{\text{EE2}}$			
O78 (OE3)	(OE3) Vout = VEE2			
O79 (OE1)	$V_{out} = V_{EE2}$			
O80 (OE2)	O ₈₀ (O _{E1})	O80 (OE2)	O80 (OE1)	
O81 (OE3)	O ₈₁ (O _{E3}) O ₈₁ (O _{E2})		O ₈₁ (O _{E2})	
O82 (OE1)	O82 (OE3) O82 (OE1)		O82 (OE3)	
•	•	•	•	
•	•	•	•	
O ₁₅₀ (O _{E3})	O150 (OE2)	О150 (ОЕ3)	O150 (OE2)	
O150 (OE3)	O150 (OE2)	O151 (OE1)	O150 (OE2)	
O 152 (OE2)	O152 (OE1)	O152 (OE2)	O152 (OE1)	
O 152 (OE2)	O152 (OE1)			
. ,	()	. ,	O153 (OE2) O154 (OE3)	
O154 (OE1)	O154 (OE3)	O154 (OE1)	О154 (ОЕ3)	

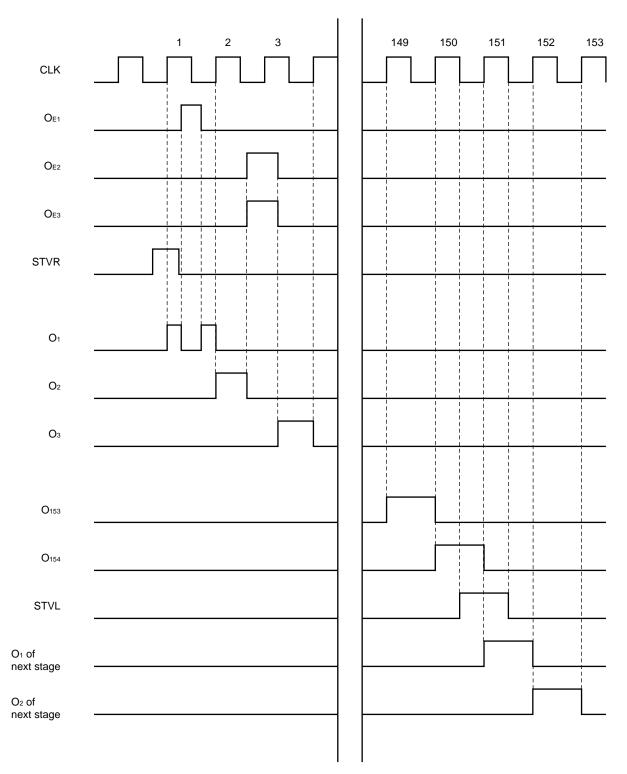
5. TIMING CHART

(1) 154 outputs, $R/\overline{L} = H O_{sel} = L$



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(2) 150 outputs, $R/\overline{L} = H O_{sel} = H$



O76 to O79 is L (VEE2) level fixation (150 output).

6. ELECTRIC SPECIFICATION

Parameter	Symbol	Rating	Unit
Supply Voltage	Vdd2	-0.5 to +28	V
Supply Voltage	Vcc	-0.5 to +7.0	V
Supply Voltage	VDD2-VEE1/2	–0.5 to 42	V
Supply Voltage	Vee1	-16.5 to +0.5	V
Supply Voltage	Vee2	VEE1 - 0.5 to +0.5	V
Input Voltage	Vı	–0.5 to Vcc + 0.5	V
Input Current	h	±10	mA
Output Current	lo	±10	mA
Operating Temperature Range	TA	-20 to +70	°C
Storage Temperature Range	Tstg	–55 to +125	°C

Absolute Maximum Ratings (TA = 25°C, Vss1 = Vss2 = 0 V)

Recommended Operating Condition (T_A = -20 to +80°C, V_{SS1} = V_{SS2} = 0 V)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	Vdd2	17		25	V
Supply Voltage	Vee1	-15		-5.0	V
Supply Voltage	Vee2	Vee1		Vee1 + 6.0	V
Supply Voltage	Vdd2 - Vee1	22		40	V
Supply Voltage	Vcc	3.0	3.3	3.6	V

Electrical Specifications (TA = -20 to +70°C, VDD1 = 25 V, VDD2 = 3.3 V \pm 0.3 V, VEE1 = VEE2 = -15 V, VSS = 0 V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Input voltage, high	Vін	CLK, STVR (STVL), R/L,	0.8 Vcc		Vcc	V
Input voltage, low	VIL	Osel, OE1-OE3	Vss		0.2 Vcc	V
Output voltage, high	Vон	STVR (STVL), Іон = –40 µА	Vcc - 0.4 ^{Note}		Vcc ^{Note}	V
Output voltage, low	Vol	STVR (STVL), Ιο _L = +40 μΑ	Vss ^{Note}		Vss + 0.4 ^{Note}	V
Output current, high	Iлон	On, $Vn = V_{DD2} - 1.0 V$			-1.0	mA
Output current, low	InOL	On, Vn = VEE2 + 1.0 V	1.0			mA
Output ON resistance	Ron	$Vn = V_{EE2} + 1.0 V \text{ or } V_{DD2} - 1.0 V$			1.0	kΩ
Input leakage current	lı∟	VI = 0 V or 3.6 V			±1.0	μA
Dynamic current	IDD2	VDD2, fclk = 30 kHz, no loads			400	μA
	lcc	Vcc1, fclk = 30 kHz, no loads			600	μA
	IEE	IEE1 + IEE2, fCLK = 30 kHz, no loads			800	μA

Note The cascade output is at the driver level (Vcc-Vss).

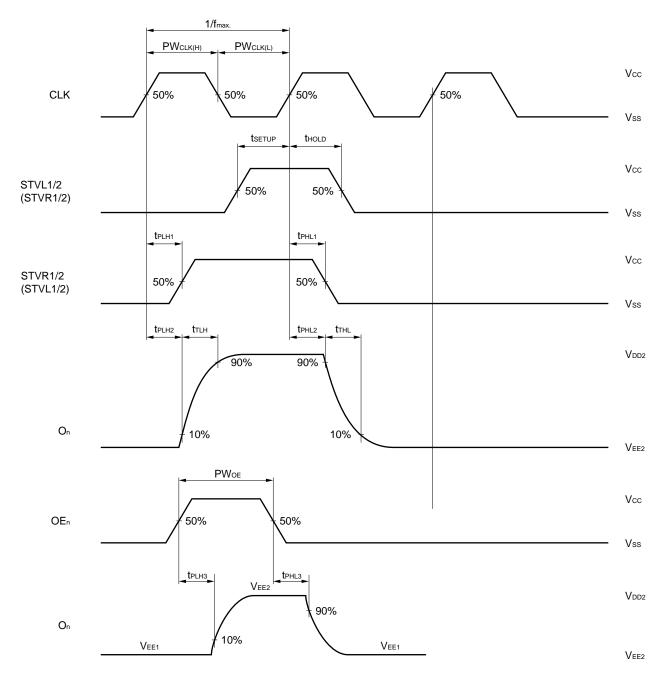
Switching Characteristics (TA = -20 to $+70^{\circ}$ C, VDD1 = 25 V, VDD2 = 3.3 V \pm 0.3 V, VEE1 = VEE2 = -15 V, Vss = 0 V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Cascade output delay time	tPHL1	C∟ = 20 pF			800	ns
	tPLH1	$CLK\toSTVL\ (STVR)$			800	ns
Driver output delay time 1	tPHL2	C∟ = 300 pF			500	ns
	tPLH2	$CLK\toOn$			500	ns
Driver output delay time 2	tphl3	C∟ = 300 pF			500	ns
	t PLH3	$O_{En} \to On$			500	ns
Output rise time	tтьн	C∟ = 300 pF			450	ns
Output fall time	tтн∟				450	ns
Input capacitance	Cı	T _A = 25°C			15	pF
Maximum clock frequency	fmax.	When connected in cascade	500			kHz

Timing Requirement (T_A = -20 to $+70^{\circ}$ C, V_{DD1} = 25 V, V_{DD2} = 3.3 V ± 0.3 V, V_{EE1} = V_{EE2} = -15 V, V_{SS} = 0 V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Clock Pulse Low Period	PWclk(H)		500			ns
Clock Pulse High Period	PWclk(L)		500			ns
Enable Pulse low period	PWOE		1.0			μs
Data Setup Time	t SETUP	STVR (STVL) $\uparrow \rightarrow$ CLK \uparrow	200			ns
Data Hold Time	t HOLD	$CLK \uparrow \to STVR \ (STVL) \downarrow$	200			ns

The rise and fall times of logic input must be $t_r = t_f = 20$ ns (10% to 90%).



7. SWITCHING CHARACTERISTICS WAVEFORM (R/L = H)

8. RECOMMENDED MOUNTING CONDITIONS

When mounting this product, please make sure that the following recommended conditions are satisfied.

For packaging methods and conditions other than those recommended below, please contact NEC sales personnel.

Mounting Condition	Mounting Method	Condition
Thermocompression	Soldering	Heating tool 300 to 350°C, heating for 2 to 3 sec; pressure 100 g (per solder)
	ACF (Adhesive Conductive Film)	Temporary bonding 70 to 100°C; pressure 3 to 8 kg/cm ² ; time 3 to 5 sec. Real bonding 165 to 180°C; pressure 25 to 45 kg/cm ² , time 30 to 40 secs. (When using the anisotropy conductive film SUMIZAC1003 of Sumitomo Bakelite, Ltd.)

Caution To find out the detailed conditions for packaging the ACF part, please contact the ACF manufacturing company. Be sure to avoid using two or more packaging methods at a time.

Reference

NEC Semiconductor Device Reliability/Quality Control System (C10983E) Quality Grades to NEC's Semiconductor Devices (C11531E) [MEMO]

[MEMO]

[MEMO]

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